IN-27 024416

NASA Contractor Report 201669



Adhesive Properties of Cured Phenylethynyl Containing Imides

Alice C. Chang Lockheed Martin Engineering & Sciences Company, Hampton, Virginia

Contract NAS1-96014

March 1997

National Aeronautics and Space Administration Langley Research Center Hampton, Virginia 23681-0001 • · ٠ •

ADHESIVE PROPERTIES OF CURED PHENYLETHYNYL CONTAINING IMIDES

A. C. Chang Lockheed Martin Engineering & Sciences Company Hampton, Virginia 23666

1. ABSTRACT

As part of a program to develop structural adhesives for high performance aerospace applications, several phenylethynyl containing oligomer blends of LaRC[™] MPEI¹ (Modified Phenylethynyl Terminated Polyimide) and a reactive plasticizer designated LaRC[™] LV-121 were prepared and evaluated. The fully imidized blends exhibited minimum melt viscosity as low as 1000 poise at 371°C. Ti/Ti lap shear specimens fabricated at 316°C under 15 psi gave RT strength of ~4300 psi and no change in strength was observed at 177°C. The chemistry and properties of this new MPEI as well as some blends of MPEI with LV-121 are presented and compared to the linear version, LaRC[™]-PETI-5.^{2,3}

2. EXPERIMENTAL

2.1 Materials Synthesis

The MPEI was synthesized as previously reported.¹ The LV-121 was synthesized under the same conditions and utilizes similar chemistry as the MPEI but is a lower molecular weight phenylethynyl containing material.

2.2 Characterization

Brookfield viscosity measurements were taken on 35 and 42 wt% solids solutions at 25°C. Differential scanning calorimetry (DSC) was performed on a Shimadzu DSC-50 calorimeter at a heating rate of 20°C/min. The T_g was taken at the inflection point of the heat flow vs. temperature curve.

2.3 Rheology

Melt viscosity measurements were performed on a Rheometrics System IV rheometer. Sample specimen disks, 1 inch in diameter and ~0.06 inch thick, were prepared by press molding of solution imidized powder at RT. The compacted resin disk was then loaded in the rheometer fixture with 1 inch parallel plates. The top plate was oscillated at a fixed strain rate of 5% and a fixed angular frequency of 10 rad/sec, while the lower plate was attached to a transducer which recorded the resultant torque. Storage (G') and loss (G'') moduli as a function of time (t) were measured at several temperatures.

2.4 Films

Poly(amide acid) solutions were poured onto clean glass plates and spread to ~30 mils thickness using a doctor's blade, then placed in a level, dust free, dry chamber until tack free. Films were cured in a circulating air oven for 1 hour each at 100, 225, and 350°C, removed from the glass plates and tested according to ASTM-D882.

2.5 Adhesive Specimens

NMP solutions (35% solids) were used to coat 112 E-glass (A1100 finish). Each coat was dried in a circulating air oven at 100 and 225°C for 1 h each. Several coats were used to provide a 12-14 mil thick tape with final volatile content of <1.5%. Titanium (Ti,6AI-4V) coupons (Pasa-Jell 107[™] surface treatment, primed with PETI-5 solution) were bonded under 1.7 - 50 psi by heating rapidly to 288 - 371°C and holding for 1 - 8 h. Four specimens of each bonding condition were tested at RT and 177°C following the guidelines of ASTM D-1002.

3. RESULTS AND DISCUSSION

Although several new MPEI compositions and different molecular weights (from 1500 to 7000 g/mole theoretical number average molecular weights) have been

prepared, the work presented herein describes only one composition and at only one molecular weight. This composition utilizes BPDA with 85% 3,4-ODA and 15% APB such that the total theoretical number average molecular weight is 5500 g/mole. This particular material has received most of the attention because it provides a direct comparison to the completely linear version, PETI-5, of the same theoretical number average molecular weight. Likewise, many different LaRC[™] LV compositions and molecular weights have been prepared, the LV-121 composition was chosen for the blends because of the similarities in chemistry with the MPEI.

The reactive plasticizers with similar composition to LV-121 but various molecular weights and their dynamic minimum melt viscosities are shown in Table 1. All the plasticizers exhibit low initial Tg and minimum melt viscosity of < 50 poise (below capability of equipment) at a temperature of ~260 °C.

As shown in Table 2, the MPEI has a higher cured T_g than PETI-5 by about 20°C when cured at either 350 or 371°C for 1 h. Furthermore, film properties are higher at both RT and 177°C for the MPEI. Tensile strength at RT has improved by almost 25% while strength at 177°C has improved by over 15%. Tensile moduli at both RT and 177°C have increased by ~25% to very high values of 570 and 411 Ksi, respectively when compared to PETI-5. There is a significant reduction in film elongation from 32% at RT for PETI-5 to 8% elongation for the MPEI material at RT.

Table 2 also shows both the melt and solution viscosities for the two materials. As shown, the MPEI has a minimum dynamic melt viscosity of 600 poise occurring at 335°C, a lower temperature by ~35°C than the minimum for PETI-5. Furthermore, the concentrated solution viscosity (35% solids) is ~2000 centipoise versus 30,000 to 40,000 centipoise for the linear PETI-5. This difference can be very important when making prepreg or adhesive tape.

Table 3 shows titanium to titanium tensile shear strengths for the MPEI when

3

bonded under several conditions. The adhesive tape had been dried to <1.5% volatile content at a final temperature of 250°C. Very good strengths were obtained at RT and there was little to no drop off in strengths when tested at 177°C. The 177°C strengths are comparable to PETI-5.

Table 4 shows titanium to titanium tensile shear strengths for the blends when bonded under several conditions. The RT strengths are lower than the MPEI in most cases but the 177°C strengths are comparable under some bonding conditions. The blends have lower melt viscosity and actually have significant adhesive strength when bonded under only 1.7 psi at 316°C.

Neat resin properties of PETI-5/LV-121 blends are shown in Table 5. The dynamic minimum viscosity had reduced from 60,000 to 7,000 poise for PETI-5 containing 10 wt.% of LV-121 plasticizer. The blends exhibit comparable LSS as PETI-5 at 177°C when processed at milder temperature and pressure which are more desirable for secondary bonding applications.

4. CONCLUSIONS

Blends of the MPEI and LaRC[™] LV-121 have been prepared and evaluated for adhesive application. The polymer blends exhibit excellent adhesive strengths and processability at 316 °C under low pressure. Blends of PETI-5 and LaRC[™] LV-121 also exhibit excellent Ti/Ti lap shear strength retention at 177 °C and lower melt viscosities than the pure PETI-5, providing easier processing conditions.

5. REFERENCE

- 1. B. J. Jensen, Poly. Prepr: 37(2), 222 (1996).
- 2. B. J. Jensen, R. G. Bryant, J. G. Smith and P.M. Hergenrother, <u>J. of Adhesion</u>, <u>54</u> (1), 57 (1995).

3. T. H. Hou, B. J. Jensen and P. M. Hergenrother, <u>J. of Composite Materials</u>, <u>30(1)</u>, 109 (1996).

.

Material	Molecular Wt	Initial Tg	Cured Tg	Minimum Melt
	g/mole	°C	°C	Viscosity, poise
LaRC [™] LV121	1266	132	^a ND	<50 @ ~250°C
LaRC [™] LV122	1817	134	232	<50 @ ~260°C
LaRC [™] LV123	2367	150	219	<50 @ ~270°C
LaRC [™] LV124	2918	155	213	<50 @ ~280°C

Table 1. Resin Properties of Reactive Plasticisers

^a not detectable.

.

Property	MPEI	PETI-5	
Tg (350°C, 1h cure)	281	260	
°C (371°C, 1 h cure)	291	263	
Film Tensile Strength, Ksi	23.3 @ RT;14.4 @ 177°C	18.8 @ RT; 12.2 @ 177°C	
Film Tensile Modulus, Ksi	570 @ RT; 411 @ 177°C	455 @ RT; 332 @ 177°C	
Film Elongation, %	8 @ RT; 9 @ 177 °C	32 @ RT; 84 @ 177°C	
Minimum Dynamic Melt	600 @ 335°C	60,000 @ 371 °C	
Viscosity, poise			
Brookfield Viscosity of	~2000 @ 35% solids	30,000-40,000 @ 35 %	
Poly(amide acid) (25°C),	~8500 @ 42% solids	solids	
centipoise			

Table 2. Properties of MPEI¹ Compared to PETI-5.

Material	Processing Conditions	Tg, °C	Ti/Ti Tensile Shear Strength, psi % Cohesive Failure RT 177°C	
MPEI	15 psi, 288°C, 8 h	278	5000 30%	4350 20%
MPEI	50 psi, 288°C, 8 h	278	4600 40%	4550 40%
MPEI	15 psi, 316°C, 8 h	290	4800 70%	4800 50%
MPEI	50 psi, 316°C, 8 h	290	4800 70%	4400 40%
MPEI	15 psi, 371°C, 1 h	299	4750 50%	
PETI-5	75 psi, 350°C, 1 h	265	7000 80%	4350 80%

Table 3.	Adhesive Properties of MPEI Compared to PETI-5. ²
----------	--

Material	1.7 psi, 8h,	15 psi, 8h,	15 psi, 8h,	15 psi, 4h,
	316°C	288°C	316°C	316°C
MPEI	2320 50%	5000 30%	4800 70%	5320 70%
	(2630 20%)	(4350 20%)	(4800 50%)	(5150 90%)
MPEI + 15%	4050 70%	4500 100%		4220 90%
LV-121	(3500 70%)	(4480 80%)		(4650 90%)
MPEI + 20%	2975 80%	3510 80%		3865 80%
LV-121	(3790 80%)	(4315 70%)		(4370 70%)
MPEI + 25%	2810 70%	3500 90%		4360 90%
LV-121	(3740 70%)	(4030 90%)		(4270 80%)
MPEI + 30%	3300 80%	3400 80%		3760 70%
LV-121	(3230 70%)	(3550 90%)		(4000 70%)

Table 4.	Ti/Ti Tensile Shear Strength (psi) and Cohesive Failure (%)
	of MPEI/LV-121 Blends at RT and (177°C).

% LV 121	Tg°C	Minimum melt η poise	Ti/Ti LSS (psi)	Bonding condition
0	265	60,000 @371°C	7000 (4350)	75 psi, 350°C, 1h
10	258	7,000 @371°C	5900 (4227)	15 psi, 316°C, 4h
15	255	1,600 @371°C	5125 (4311)	15 psi, 316°C, 4h
20	253	1,000 @371°C	5130 (3980)	15 psi, 316°C, 4h

Table 5. Neat Resin Properties of PETI-5/LV 121 Blends and Ti/Ti Lap Shear Strength(LSS) at RT and (177°C)

REPORT DOCUMENTATION PAGE			Form Approved OMB No. 0704-0188			
Public reporting burden for this collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing the burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Management and Budget, Paperwork Reduction Project (0704-0188), Washington, DC 20503.						
1. AGENCY USE ONLY (Leave Bla		3. REPORT TYP Contractor Re	PE AND DATES C	OVERED		
4. TITLE AND SUBTITLE ADHESIVE PROPERTIES OF CURED PHENYLETHYNYL CONTAINING IMIDES			C NAS1-	G NUMBERS 96014 63-50-01		
6. AUTHOR(S) Alice C. Chang						
7. PERFORMING ORGANIZATION				8. PERFORMING ORGANIZATION REPORT NUMBER		
Hampton, VA 23666	ering & Sciences Company					
9. SPONSORING/MONITORING A		S(ES)		ORING/MONITORING EPORT NUMBER		
National Aeronautics and Space Administration Langley Research Center Hampton, Virginia 23681-0000				R-201669		
11. SUPPLEMENTARY NOTES			I			
Langley Technical Monitor:	James F. Dezem					
12a. DISTRIBUTION/AVAILABILIT	Y STATEMENT		12b. DISTR	IBUTION CODE		
Unclassified-Unlimited Subject Category 27						
13. ABSTRACT (Maximum 200 wor						
As part of a program phenylethynyl containing oligome and evaluated. The fully imidiz specimens fabricated at 316°C ur The chemistry and properties of the the linear version, LARC [™] -PET	ed blends exhibited minimum ı der 15 psi gave RT strength of - his new MPEI as well as some	active plasticizer nelt viscosity as l -4300 psi and no	designated LaRC low as 1000 poise change in strengtl	[™] LV-121 were prepared at 371°C. Ti/Ti lap shear n was observed at 177°C.		
14. SUBJECT TERMS LaRC [™] -PETI-5, Polyimides, LaRC [™] MPEI, LaRC [™] LV-121, Lap Shear Strength.			th. 11	15. NUMBER OF PAGES 11 16. PRICE CODE		
17. SECURITY CLASSIFICATION	18. SECURITY CLASSIFICATIO	N 19. SECURITY	CLASSIFICATION	20. LIMITATION OF		
OF REPORT Unclassified	OF THIS PAGE Unclassified	OF ABSTRAC		ABSTRACT		
NSN 7540-01-280-5500		.		ard Form 298 (Rev. 2-89) bed by ANSI Std. Z39-18 2		